

DATA SHEET

General Description

The IDT5T9304 differential clock buffer has a user-selectable differential input to four LVDS outputs. The fanout from a differential input to four LVDS outputs reduces loading on the preceding driver and provides an efficient clock distribution network. The IDT5T9304 can act as a translator from a differential HSTL, eHSTL, LVEPECL (2.5V), LVPECL (3.3V), CML, or LVDS input to LVDS outputs. A single-ended 3.3V / 2.5V LVTTL input can also be used to translate to LVDS outputs. The redundant input capability allows for an asynchronous change-over from a primary clock source to a secondary clock source. Selectable reference inputs are controlled by SEL.

The IDT5T9304 outputs can be asynchronously enabled/disabled. When disabled, the outputs will drive to the value selected by the GL pin. Multiple power and grounds reduce noise.

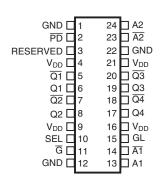
Applications

Clock distribution

Features

- Guaranteed low skew: 50ps (maximum)
- Very low duty cycle distortion: 125ps (maximum)
- Propagation delay: 1.75ns (maximum)
- Up to 450MHz operation
- Selectable inputs
- Hot insertable and over-voltage tolerant inputs
- 3.3V/2.5V LVTTL, HSTL eHSTL, LVEPECL (2.5V), LVPECL (3.3V), CML or LVDS input interface
- Selectable differential inputs to four LVDS outputs
- 2.5V V_{DD}
- 0°C to 70°C ambient operating temperature
- Available in standard (RoHS 5) and lead-free (RoHS 6) packages

Pin Assignment



IDT5T9304

24-Lead TSSOP
4.4mm x 7.8mm x 1.0mm package body
G Package
Top View

Block Diagram

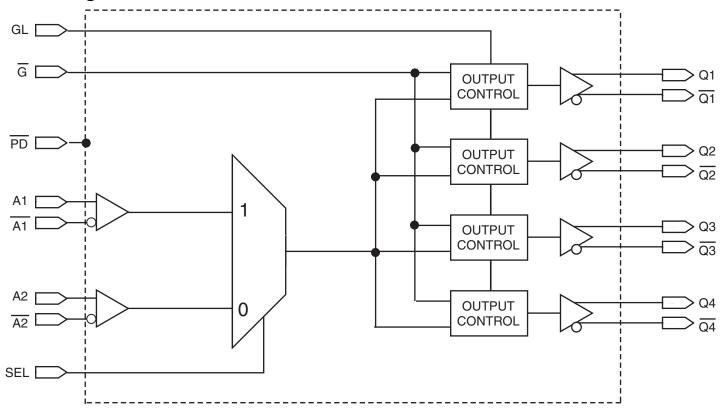


Table 1. Pin Descriptions

Number	Name		Туре	Description
1, 12, 22	GND		Power	Power supply return for all power.
2	PD	Input	LVTTL	Power-down control. Shuts off entire chip. If LOW, the device goes into low power mode. Inputs and outputs are disabled. Both Qx and \overline{Qx} outputs will pull to VDD. Set HIGH for normal operation. ⁽³⁾
3	RESERVED	Reserved		Reserved pin.
4, 9, 16, 21	V_{DD}		Power	Power supply for the device core and inputs.
5, 7, 18, 20	Q1, Q2, Q4, Q3	Output	LVDS	Complementary differential clock outputs.
6, 8, 17, 19	Q1, Q2, Q4, Q3	Output	LVDS	Differential clock outputs.
10	SEL	Input	LVTTL	Reference clock select. When LOW, selects A2 and $\overline{\text{A2}}$. When HIGH, selects A1 and $\overline{\text{A1}}$.
11	G	Input	LVTTL	Gate control for differential outputs Q1 and $\overline{Q1}$ through Q4 and $\overline{Q4}$. When \overline{G} is LOW, the differential outputs are active. When \overline{G} is HIGH, the differential outputs are asynchronously driven to the level designated by GL ⁽²⁾ .
13, 24	A1, A2	Input	Adjustable (1, 4)	Clock input. A[1:2] is the "true" side of the differential clock input.
14, 23	Ā1, Ā2	Input	Adjustable ^(1, 4)	Complementary clock inputs. $\overline{A[1:2]}$ is the complementary side of A[1:2]. For LVTTL single-ended operation, $\overline{A[1:2]}$ should be set to the desired toggle voltage for A[1:2]: 3.3V LVTTL VREF = 1650mV 2.5V LVTTL VREF = 1250mV
15	GL	Input	LVTTL	Specifies output disable level. If HIGH, Qx outputs disable HIGH and $\overline{\text{Qx}}$ outputs disable LOW. If LOW, Qx outputs disable LOW and $\overline{\text{Qx}}$ outputs disable HIGH.

NOTES:

1. Inputs are capable of translating the following interface standards:

Single-ended 3.3V and 2.5V LVTTL levels

Differential HSTL and eHSTL levels

Differential LVEPECL (2.5V) and LVPECL (3.3V) levels

Differential LVDS levels

Differential CML levels

- 2. Because the gate controls are asynchronous, runt pulses are possible. It is the user's responsibility to either time the gate control signals to minimize the possibility of runt pulses or be able to tolerate them in down stream circuitry.
- 3. It is recommended that the outputs be disabled before entering power-down mode. It is also recommended that the outputs remain disabled until the device completes power-up after asserting PD.
- 4. The user must take precautions with any differential input interface standard being used in order to prevent instability when there is no input signal.

Table 2. Pin Characteristics (TA = +25°C, F = 1.0MHz)

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
C _{IN}	Input Capacitance			3		pF

NOTE: This parameter is measured at characterization but not tested.

Function Tables

Table 3A. Gate Control Output Table

Control Output		Outputs		
GL	G	Q[1:4]	Q[1:4]	
0	0	Toggling	Toggling	
0	1	LOW	HIGH	
1	0	Toggling	Toggling	
1	1	HIGH	LOW	

Table 3B. Input Selection Table

Selection SEL pin	Inputs
0	A2, A2
1	A1, A1

Absolute Maximum Ratings

NOTE: Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics or AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

Item	Rating
Power Supply Voltage, V _{DD}	-0.5V to +3.6V
Input Voltage, V _I	-0.5V to +3.6V
Output Voltage, V _O Not to exceed 3.6V	-0.5 to V _{DD} +0.5V
Storage Temperature, T _{STG}	-65°C to 150°C
Junction Temperature, T _J	150°C

Recommended Operating Range

Symbol	Description	Minimum	Typical	Maximum	Units
Ta	Ambient Operating Temperature	0	25	70	°C
V _{DD}	Internal Power Supply Voltage	2.3	2.5	2.7	V

DC Electrical Characteristics

Table 4A. LVDS Power Supply DC Characteristics⁽¹⁾, $V_{DD} = 2.5V \pm 0.2V$, $T_A = 0$ °C to 70°C

Symbol	Parameter	Test Conditions	Minimum	Typical ⁽²⁾	Maximum	Units
I _{DDQ}	Quiescent V _{DD} Power Supply Current	V _{DD} = Max., All Input Clocks = LOW ⁽²⁾ ; Output enabled			240	mA
I _{TOT}	Total Power V _{DD} Supply Current	V _{DD} = 2.7V; F _{REFERENCE} Clock = 450MHz			250	mA
I _{PD}	Total Power Down Supply Current	PD = LOW			5	mA

NOTE 1. These power consumption characteristics are for all the valid input interfaces and cover the worst case conditions.

Table 4B. LVCMOS/LVTTL DC Characteristics⁽¹⁾, $V_{DD} = 2.5V \pm 0.2V$, $T_A = 0$ °C to 70°C

Symbol	Parameter	Test Conditions	Minimum	Typical ⁽²⁾	Maximum	Units
I _{IH}	Input High Current	$V_{DD} = 2.7V$			±5	μΑ
I _{IL}	Input Low Current	$V_{DD} = 2.7V$			±5	μΑ
V _{IK}	Clamp Diode Voltage	$V_{DD} = 2.3V, I_{IN} = -18mA$		-0.7	-1.2	V
V _{IN}	DC Input Voltage		-0.3		3.6	V
V _{IH}	DC Input High Voltage		1.7			V
V_{IL}	DC Input Low Voltage				0.7	V
V _{THI}	DC Input Threshold Crossing Voltage			V _{DD} /2		V
V	Single-Ended Reference Voltage (3)	3.3V LVTTL		1.65		V
V _{REF}	Single-Ended Reference Voltage V	2.5V LVTTL		1.25		V

NOTE 1. See Recommended Operating Range table.

Table 4C. Differential DC Characteristics⁽¹⁾, $V_{DD} = 2.5V \pm 0.2V$, $T_A = 0$ °C to 70°C

Symbol	Parameter	Test Conditions	Minimum	Typical ⁽²⁾	Maximum	Units
I _{IH}	Input High Current	V _{DD} = 2.7V			±5	μΑ
I _{IL}	Input Low Current	V _{DD} = 2.7V			±5	μΑ
V _{IK}	Clamp Diode Voltage	V _{DD} = 2.3V, I _{IN} = -18mA		-0.7	-1.2	V
V_{IN}	DC Input Voltage		-0.3		3.6	V
V_{DIF}	DC Differential Voltage ⁽³⁾		0.1			V
V _{CM}	DC Common Mode Input Voltage ⁽⁴⁾		0.05		V_{DD}	V

NOTE 1. See Recommended Operating Range table.

NOTE 2. The true input is held LOW and the complementary input is held HIGH.

NOTE 2. Typical values are at $V_{DD} = 2.5V$, +25°C ambient.

NOTE 3. For A[1:2] single-ended operation, \overline{A} [1:2] is tied to a DC reference voltage.

NOTE 2. Typical values are at $V_{DD} = 2.5V$, +25°C ambient.

NOTE 3. VDIF specifies the minimum input differential voltage (VTR - VCP) required for switching where VTR is the "true" input level and VCP is the "complement" input level. The DC differential voltage must be maintained to guarantee retaining the existing HIGH or LOW input. The AC differential voltage must be achieved to guarantee switching to a new state.

NOTE 4. Vcm specifies the maximum allowable range of (VTR + VCP) /2.

Table 4D. LVDS DC Characteristics⁽¹⁾, V_{DD} = 2.5V±0.2V, T_A = 0°C to 70°C

Symbol	Parameter	Test Conditions	Minimum	Typical ⁽²⁾	Maximum	Units
V _{OT(+)}	Differential Output Voltage for the True Binary State		247		454	mV
V _{OT(-)}	Differential Output Voltage for the False Binary State		247		454	mV
ΔV _{OT}	Change in V _{OT} Between Complementary Output States				50	mV
V _{OS}	Output Common Mode Voltage (Offset Voltage)		1.125	1.2	1.375	V
ΔV _{OS}	Change in V _{OS} Between Complementary Output States				50	mV
Ios	Outputs Short Circuit Current	V _{OUT+ and} V _{OUT} = 0V		12	24	mA
I _{OSD}	Differential Outputs Short Circuit Current	$V_{OUT+} = V_{OUT-}$		6	12	mA

NOTE 1. See Recommended Operating Range table.

NOTE 2. Typical values are at V_{DD} = 2.5V, +25°C ambient.

AC Electrical Characteristics

Table 5A. HSTL Differential Input AC Characteristics, $V_{DD} = 2.5V \pm 0.2V$, $T_A = 0$ °C to 70°C

Symbol	Parameter	Value	Units
V_{DIF}	Input Signal Swing ⁽¹⁾	1	V
V _X	Differential Input Signal Crossing Point ⁽²⁾	750	mV
D _H	Duty Cycle	50	%
V_{THI}	Input Timing Measurement Reference Level ⁽³⁾	Crossing Point	V
t _R / t _F	Input Signal Edge Rate ⁽⁴⁾	2	V/ns

NOTE 1. The 1V peak-to-peak input pulse level is specified to allow consistent, repeatable results in an automatic test equipment (ATE) environment. This device meets the VDIF (AC) specification under actual use conditions.

NOTE 2. A 750mV crossing point level is specified to allow consistent, repeatable results in an automatic test equipment (ATE) environment. This device meets the Vx specification under actual use conditions.

NOTE 3. In all cases, input waveform timing is marked at the differential cross-point of the input signals.

NOTE 4. The input signal edge rate of 2V/ns or greater is to be maintained in the 20% to 80% range of the input waveform.

Table 5B. eHSTL AC Differential Input Characteristics, $V_{DD} = 2.5V \pm 0.2V$, $T_A = 0$ °C to 70°C

Symbol	Parameter	Value	Units
V_{DIF}	Input Signal Swing ⁽¹⁾	1	V
V _X	Differential Input Signal Crossing Point ⁽²⁾	900	mV
D _H	Duty Cycle	50	%
V _{THI}	Input Timing Measurement Reference Level ⁽³⁾	Crossing Point	V
t _R / t _F	Input Signal Edge Rate ⁽⁴⁾	2	V/ns

NOTE 1. The 1V peak-to-peak input pulse level is specified to allow consistent, repeatable results in an automatic test equipment (ATE) environment. This device meets the VDIF (AC) specification under actual use conditions.

NOTE 2. A 900mV crossing point level is specified to allow consistent, repeatable results in an automatic test equipment (ATE) environment. This device meets the Vx specification under actual use conditions.

NOTE 3. In all cases, input waveform timing is marked at the differential cross-point of the input signals.

NOTE 4. The input signal edge rate of 2V/ns or greater is to be maintained in the 20% to 80% range of the input waveform.

Table 5C. LVEPECL (2.5V) and LVPECL (3.3V) Differential Input AC Characteristics, $V_{DD} = 2.5V \pm 0.2V$, $T_A = 0$ °C to 70°C to 70

Symbol	Parameter		Maximum	Units
V_{DIF}	Input Signal Swing ⁽¹⁾		732	mV
V _X Differential Input Cross Point Voltage ⁽²⁾	LVEPECL	1082	mV	
	Differential input Cross Point Voltage	LVPECL	1880	mV
D _H	Duty Cycle		50	%
V_{THI}	Input Timing Measurement Reference Level ⁽³⁾		Crossing Point	V
t _R / t _F	Input Signal Edge Rate ⁽⁴⁾		2	V/ns

NOTE 1. The 732mV peak-to-peak input pulse level is specified to allow consistent, repeatable results in an automatic test equipment (ATE) environment. This device meets the VDIF (AC) specification under actual use conditions.

NOTE 2. A 1082mV LVEPECL (2.5V) and 1880mV LVPECL (3.3V) crossing point level is specified to allow consistent, repeatable results in an automatic test equipment (ATE) environment. This device meets the Vx specification under actual use conditions.

NOTE 3. In all cases, input waveform timing is marked at the differential cross-point of the input signals.

NOTE 4. The input signal edge rate of 2V/ns or greater is to be maintained in the 20% to 80% range of the input waveform.

Table 5D. LVDS Differential Input AC Characteristics, $T_A = 0$ °C to 70°C

Symbol	Parameter	Maximum	Units
V_{DIF}	Input Signal Swing ⁽¹⁾	400	mV
V _X	Differential Input Cross Point Voltage ⁽²⁾	1.2	V
D _H	Duty Cycle	50	%
V_{THI}	Input Timing Measurement Reference Level ⁽³⁾	Crossing Point	V
t _R / t _F	Input Signal Edge Rate ⁽⁴⁾	2	V/ns

NOTE 1. The 400mV peak-to-peak input pulse level is specified to allow consistent, repeatable results in an automatic test equipment (ATE) environment. This device meets the VDIF (AC) specification under actual use conditions.

NOTE 2. A 1.2V crossing point level is specified to allow consistent, repeatable results in an automatic test equipment (ATE) environment. This device meets the Vx specification under actual use conditions.

NOTE 3. In all cases, input waveform timing is marked at the differential cross-point of the input signals.

NOTE 4. The input signal edge rate of 2V/ns or greater is to be maintained in the 20% to 80% range of the input waveform.

Table 5E. AC Differential Input Characteristics⁽¹⁾, $V_{DD} = 2.5V \pm 0.2V$, $T_A = 0$ °C to 70°C

Symbol	Parameter	Minimum	Typical	Maximum	Units
V _{DIF}	AC Differential Voltage ⁽²⁾	0.1		3.6	V
V _X	Differential Input Cross Point Voltage	0.05		V_{DD}	V
V_{CM}	Common Mode Input Voltage Range ⁽³⁾	0.05		V_{DD}	V
V _{IN}	Input Voltage	-0.3		3.6	V

NOTE 1. The output will not change state until the inputs have crossed and the minimum differential voltage range defined by V_{DIF} has been met or exceeded.

NOTE 2. V_{DIF} specifies the minimum input voltage ($V_{TR} - V_{CP}$) required for switching where V_{TR} is the "true" input level and V_{CP} is the "complement" input level. The AC differential voltage must be achieved to guarantee switching to a new state.

NOTE 3. V_{CM} specified the maximum allowable range of $(V_{TR} + V_{CP})$ /2.

Table 5F. AC Characteristics^(1,5), $V_{DD} = 2.5V \pm 0.2V$, $T_A = 0$ °C to 70°C

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
tsk(o)	Same Device Output Pin-to-Pin Skew (2)				50	ps
tsk(p)	Pulse Skew ⁽³⁾				125	ps
tsk(pp)	Part-to-Part Skew ⁽⁴⁾				300	ps
tp _{LH}	Propagation Delay, Low-to-High	A Crosspoint to Qn, Qn		1.25	1.75	ns
tp _{HL}	Propagation Delay, High-to-Low	Crosspoint		1.25	1.75	ns
fo	Frequency Range ⁽⁶⁾				450	MHz
t _{PGE}	Output Gate Enable Crossing VTHI-to-Qn/Qn Crosspoint				3.5	ns
t _{PGD}	Output Gate Enable Crossing VTHI-to-Qn/Qn Crosspoint Driven to Designated Level				3.5	ns
t _{PWRDN}	PD Crossing V_{THI} -to- $Qn = V_{DD}$, $\overline{Qn} = V_{DD}$				100	μS
t _{PWRUP}	Output Gate Disable Crossing V _{THI} to Qn/Qn Driven to Designated Level				100	μS
t _R / t _F	Output Rise/Fall Time ⁽⁶⁾	20% to 80%	125		600	ps

NOTE. Electrical parameters are guaranteed over the specified ambient operating temperature range, which is established when the device is mounted in a test socket with maintained transverse airflow greater than 500 lfpm. The device will meet specifications after thermal equilibrium has been reached under these conditions.

NOTE 1. AC propagation measurements should not be taken within the first 100 cycles of startup.

NOTE 2. Skew measured between Crosspoint of all differential output pairs under identical input and output interfaces, transitions and load conditions on any one device.

NOTE 3. Skew measured is the difference between propagation delay times tp_{HL} and tp_{LH} of any differential output pair under identical input and output interfaces, transitions and load conditions on any one device.

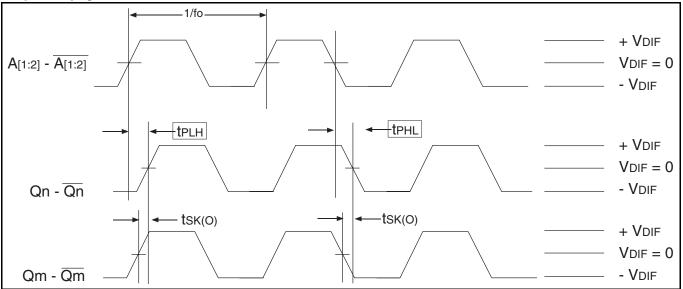
NOTE 4. Skew measured is the magnitude of the difference in propagation times between any single differential output pair of two devices, given identical transitions and load conditions at identical VDD levels and temperature.

NOTE 5. All parameters are tested with a 50% input duty cycle.

NOTE 6. Guaranteed by design but not production tested.

Differential AC Timing Waveforms

Output Propagation and Skew Waveforms

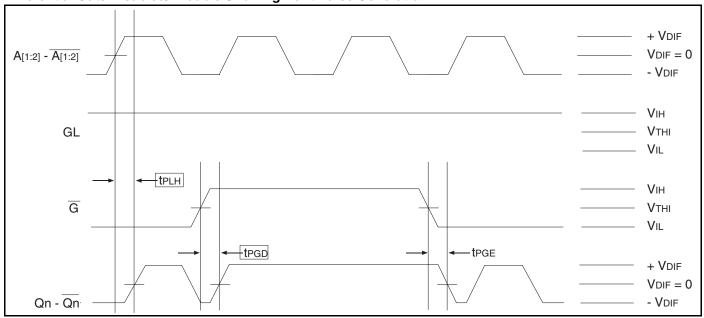


NOTE 1: Pulse skew is calculated using the following expression:

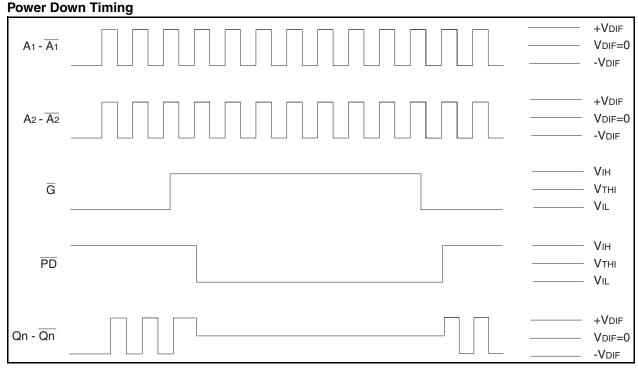
 $tsk(p) = |tp_{HL} - tp_{LH}|$

Note that the tp_{HL} and tp_{LH} shown above ae not valid measurements for this calculation because they are not taken from the same pulse. NOTE 2: AC propagation measurements should not be taken within the first 100 cycles of startup.

Differential Gate Disabled/Endable Showing Runt Pulse Generation



NOTE 1: As shown, it is possible to generate runt pulses on gate disable and enable of the outputs. It is the user's responsibility to time the \overline{G} signal to avoid this problem.



NOTE 1: It is recommended that outputs be disabled before entering power-down mode. It is also recommended that the outputs remain disabled until the device completes power-up after asserting \overline{PD} .

NOTE 2: The Power Down Timing diagram assumes that GL is HIGH.

NOTE 3: It should be noted that during power-down mode, the outputs are both pulled to V_{DD} . In the *Power Down Timing* diagram this is shown when $Q_{DI} = 0$.

Test Circuit for Differential Input

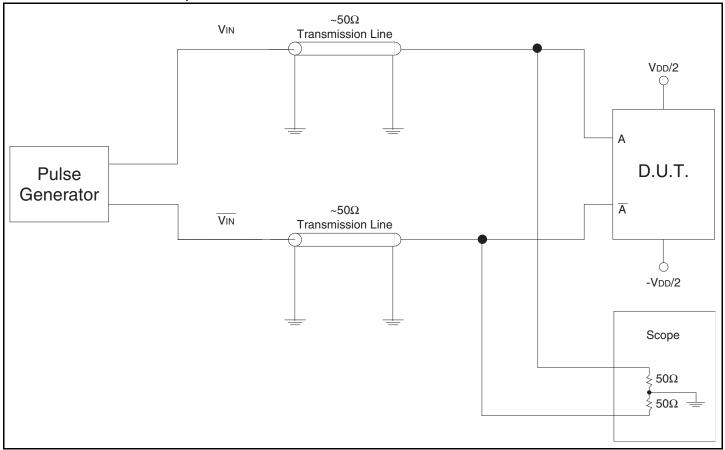
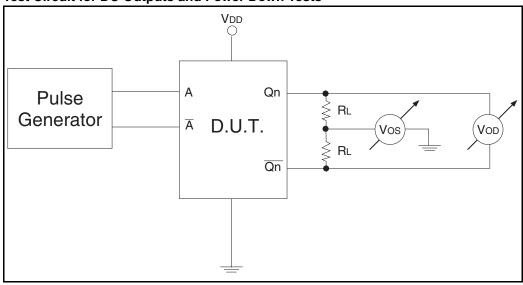


Table 6A. Differential Input Test Conditions

Symbol	$V_{DD} = 2.5V \pm 0.2V$	Unit
V_{THI} Crossing of A and \overline{A}		V

Test Circuit for DC Outputs and Power Down Tests



Test Circuit for Propagation, Skew, and Gate Enable/Disable Timing

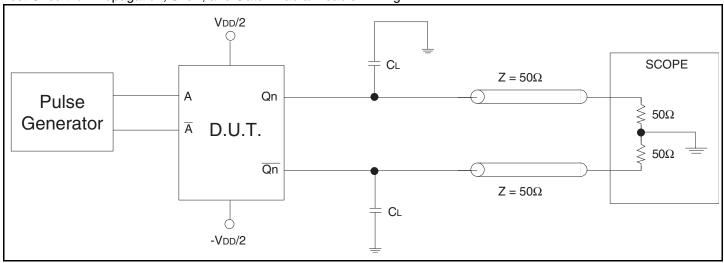


Table 6B. Differential Input Test Conditions

Symbol	$V_{DD} = 2.5V \pm 0.2V$	Unit
C	0 ⁽¹⁾	pF
OL	8 ^(1,2)	pF
R _L	50	Ω

NOTE 1: Specifications only apply to "Normal Operations" test condition. The T_{IA}/E_{IA} specification load is for reference only. NOTE 2: The scope inputs are assumed to have a 2pF load to ground. T_{IA}/E_{IA} – 644 specifies 5pF between the output pair. With C_L = 8pF, this gives the test circuit appropriate 5pF equivalent load.

Package Outline and Package Dimensions

Package Outline - G Suffix for 24 Lead TSSOP

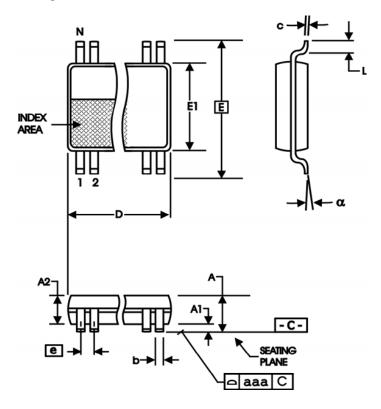


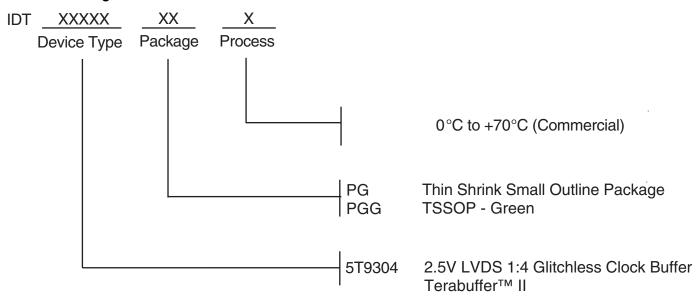
Table 7. Package Dimensions

All Dimensions in Millimeters				
Symbol	Minimum	Maximum		
N	24			
Α		1.20		
A1	0.5	0.15		
A2	0.80	1.05		
b	0.19	0.30		
С	0.09	0.20		
D	7.70	7.90		
E	6.40 Basic			
E1	4.30	4.50		
е	0.65 Basic			
L	0.45	0.75		
α	0°	8°		
aaa		0.10		

Reference Document: JEDEC Publication 95, MO-153

Ordering Information

Table 8. Ordering Information



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